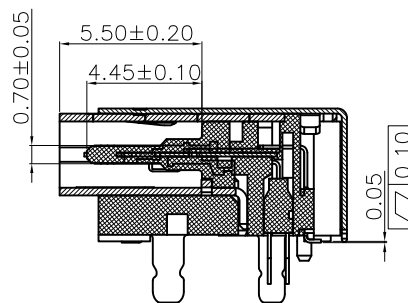
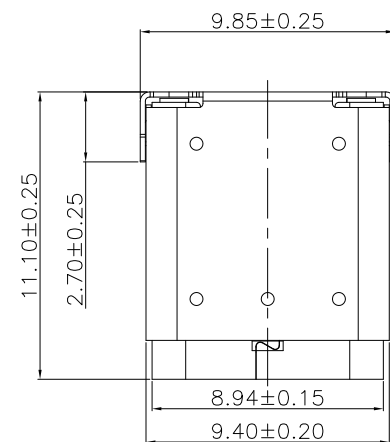


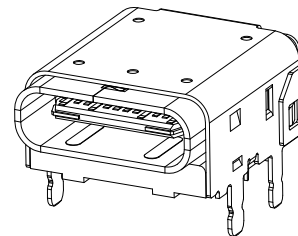
HSF Compliant

REV.	ECN NO.	DESCRIPTION	DRAW	CHECK	APPD.	DATE
A0	—	新版发行	HL.W	BENDEE	BENDEE	19-08-01

A



SECTION A-A
SCALE 1:1



料号备注										R=PACK-R0126	
CT	3	F	035	M	×	×	R	×	×	×	×

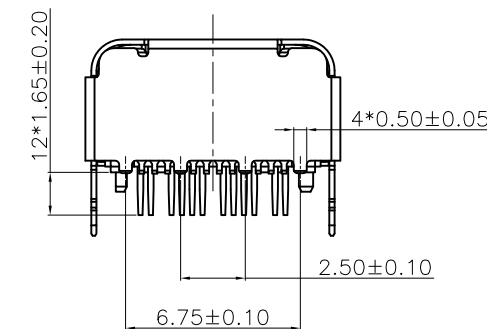
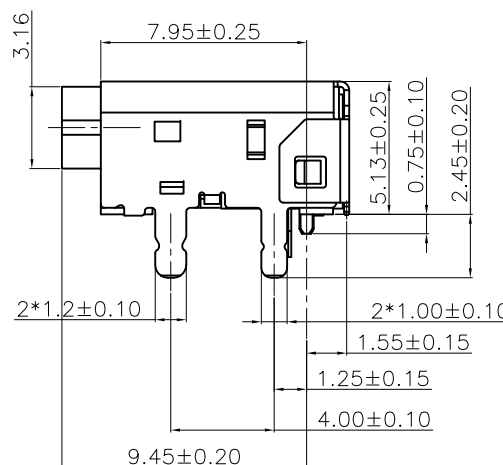
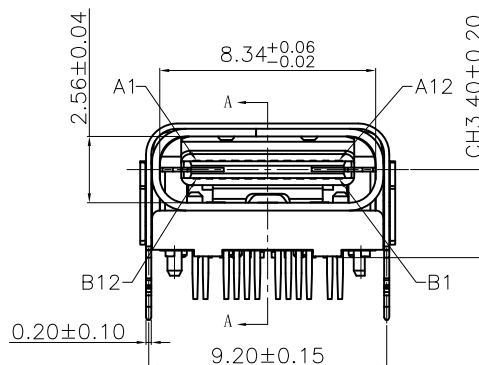
12=半金雾锡1U"
13=半金雾锡3U"
14=半金雾锡5U"
15=半金雾锡15U"
16=半金雾锡30U"

00=LCP黑不锈钢壳镀镍

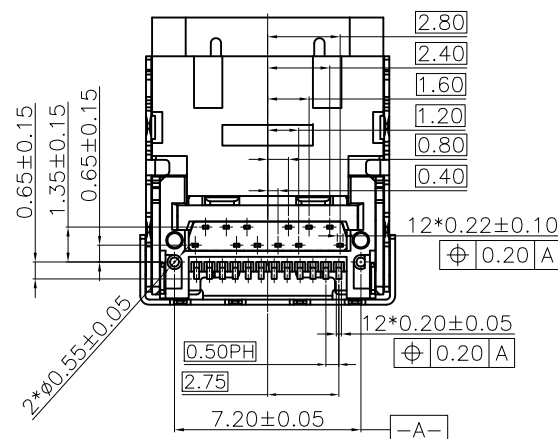
R=ROHS2.0标准
W=无卤+ROHS2.0
H=REACH标准

B=盐雾24H
C=盐雾48H

B



C



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Dong Guan XingKeJieXin Electronics Co.,Ltd

UNLESS OTHERWISE SPECIFIED TOLERANCES		APPROVAL	日期	品名	USB 3.1 GEN2 TYPE C(TBT) RECEPTACLE	
X.	+/-	制图	HL.W	规格	24P SMT+DIP CH3.4 L11.10-A	
.X	+/-	审核				
.XX	+/-	核准				
FRACTIONS	+/-	文件位置		料号	SEE TABLE	
ANGLES	+/-	ANGLE OF PROJECTION		字张	工程图号:	版本.
DIMENSIONS				A4	DWG-CTCF-035	A0
(METRIC)	(MM)			比例	1 : 1	状态码 A
				页数	1	OF 2

D

A

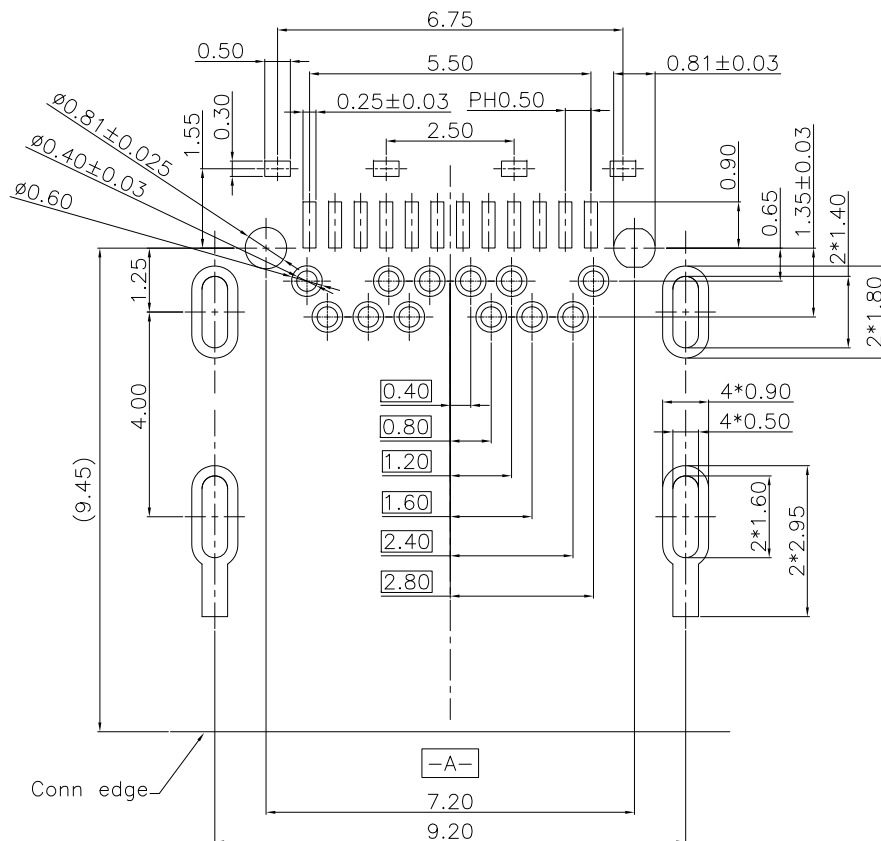
B

C

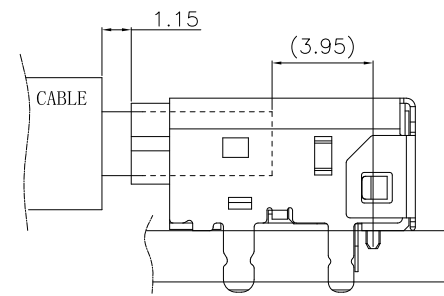
D

HSF Compliant

REV.	ECN NO.	DESCRIPTION	DRAW	CHECK	APPD.	DATE
A0	—	新版发行	HL.W	BENDEE	BENDEE	19-08-01



RECOMMENDED PCB LAYOUT(TOP) SCALE 2:1
TOLERANCES:±0.05MM



Mating

料号备注

CT 3 F 035 M XX R XX XX X

12=半金雾锡1U"
13=半金雾锡3U"
14=半金雾锡5U"
15=半金雾锡15U"
16=半金雾锡30U"

00=LCP黑不锈钢壳电镀

R=PACK-R0126

R=ROHS2.0标准
W=无卤+ROHS2.0
H=REACH标准

B=盐雾24H
C=盐雾48H

Specifications:

- Electrical performance:
- Contact resistance: 40mΩ max for initial. 10mΩ change after test. measure at 20mv, 100mA.
- Dielectric withstanding voltage:AC 100V(rms).
- Insulation resistance:100MΩ min.
- Contact current rating:
3A for Vbus pin;1.25A for Vconn and GND pin;0.25A for all the other pin.
- Voltage: 5 Vac (rms).
- mechanical performance:
- Mating force:5~20N
- Unmating force:8~20N Initial test, 6~20N After test
- Durability:10,000 cycles.
- Environmental performance:
- Temperature range:
- Operating temperature:-25°to+85°.
- Storage temperature:-20°to+60°.
- Material:
- Housing:LCP Black,UL94-V0.
- Contact:C7025,T=0.12mm
- Mid-plate: SUS301,T=0.15mm
- Shell-in:SUS304 T=0.30mm
- Shell-out:SUS301 T=0.20mm
- Plating specification:
- Contact:Au(see table) plated on contact area Matte Tin plated 100u"min on solder area;Nickel 50u"min underplating over all.
- Shell-out:Nickel 30u"min plating over all.

A1	GND	B12	GND
A2	SSTXP1	B11	SSRXN1
A3	SSTXN1	B10	SSRXN1
A4	VBUS	B9	VBUS
A5	CC1	B8	SBU2
A6	DP1	B7	DN2
A7	DN1	B6	DP2
A8	SBU1	B5	CC2
A9	VBUS	B4	VBUS
A10	SSRXN2	B3	SSTXN2
A11	SSRXP2	B2	SSTXP2
A12	GND	B1	GND
PIN	SIGNAL NAME	PIN	SIGNAL NAME



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UNLESS OTHERWISE SPECIFIED
TOLERANCES

X.	+/-	METRIC	0.30
.X	+/-	0.25	
.XX	+/-	0.15	
FRACTIONS	+/-		
ANGLES	+/-	2.00°	
DIMENSIONS			
(METRIC)		(MM)	

APPROVAL

制图	HL.W	日期	2019.08.01
审核			
核准			
文件位置			

品名规格

品名规格	USB 3.1 GEN2 TYPE C(TBT) RECEPTACLE 24P SMT+DIP CH3.4 L11.10-A
料号	SEE TABLE
字库	工程图号: DWG-CTCF-035
比例	1 : 1

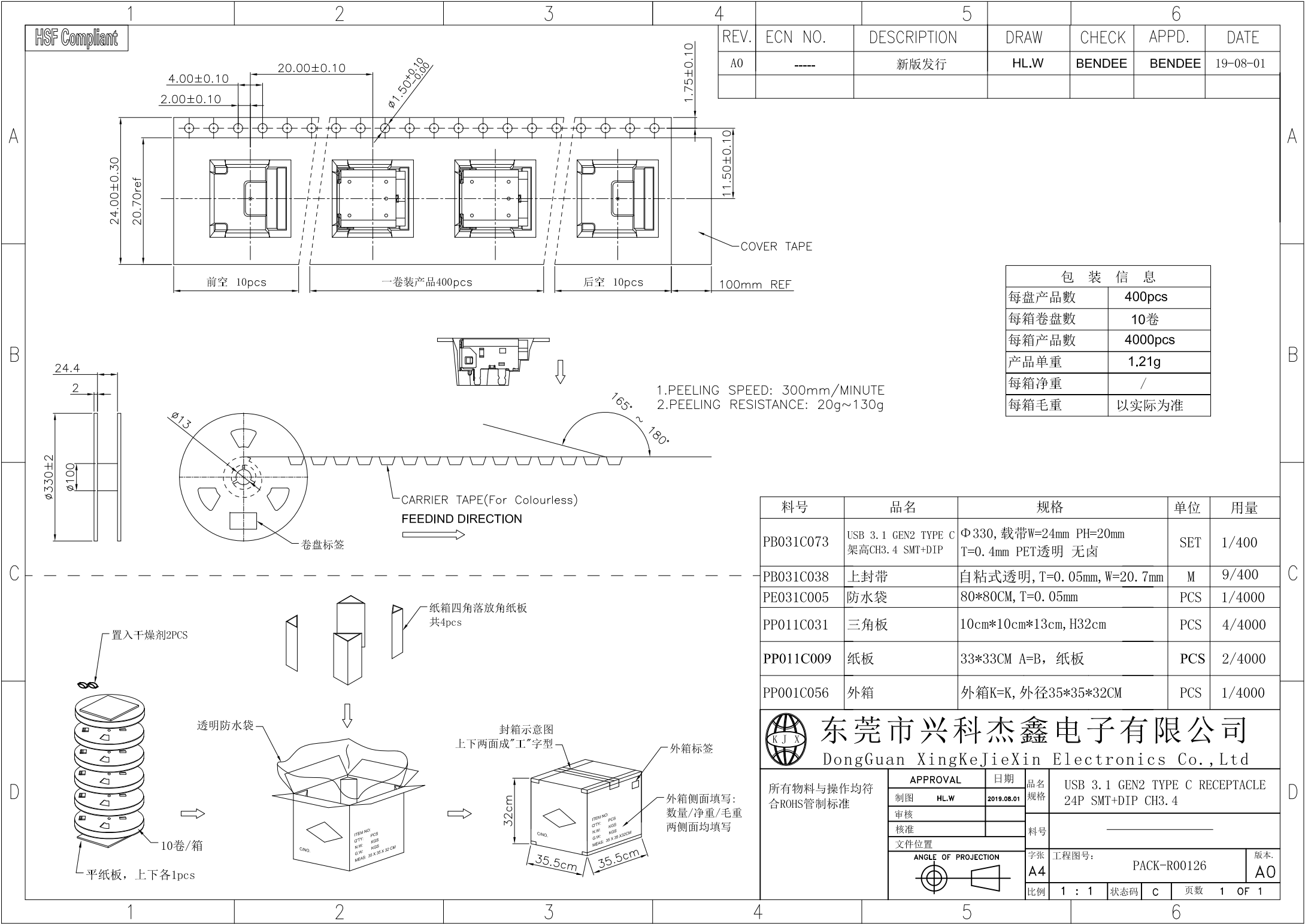
状态码

状态码	A
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页数

页数	2 OF 2
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版本: A0



REV.	ECN NO.	DESCRIPTION	DRAW	CHECK	APPD.	DATE
A0	----	新版发行	HL.W	BENDEE	BENDEE	19-08-01

包 装 信 息	
每盘产品数	400pcs
每箱卷盘数	10卷
每箱产品数	4000pcs
产品单重	1.21g
每箱净重	/
每箱毛重	以实际为准

料号	品名	规格	单位	用量
PB031C073	USB 3.1 GEN2 TYPE C 架高CH3.4 SMT+DIP	Φ 330, 载带W=24mm PH=20mm T=0.4mm PET透明 无卤	SET	1/400
PB031C038	上封带	自粘式透明, T=0.05mm, W=20.7mm	M	9/400
PE031C005	防水袋	80*80CM, T=0.05mm	PCS	1/4000
PP011C031	三角板	10cm*10cm*13cm, H32cm	PCS	4/4000
PP011C009	纸板	33*33CM A=B, 纸板	PCS	2/4000
PP001C056	外箱	外箱K=K, 外径35*35*32CM	PCS	1/4000



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DongGuan XingKeJieXin Electronics Co., Ltd

所有物料与操作均符合ROHS管制标准	APPROVAL	日期	品名	USB 3.1 GEN2 TYPE C RECEPTACLE 24P SMT+DIP CH3.4	
	制图 HL.W	2019.08.01	规格		
	审核		料号		
	核准		文件位置		
ANGLE OF PROJECTION 			字张	工程图号:	版本.
			A4	PACK-R00126	A0
			比例	1 : 1	状态码 C
			页数	1	OF 1